

HX432C16PB3K4/16

16GB (4GB 512M x 64-Bit x 4 pcs.)
 DDR4-3200 CL16 288-Pin DIMM



SPECIFICATIONS

CL(IDD)	17 cycles
Row Cycle Time (tRCmin)	45.75ns(min.)
Refresh to Active/Refresh Command Time (tRFCmin)	260ns(min.)
Row Active Time (tRASmin)	32ns(min.)
Maximum Operating Power	TBD W*
UL Rating	94 V - 0
Operating Temperature	0° C to +85° C
Storage Temperature	-55° C to +100° C

*Power will vary depending on the SDRAM used.

DESCRIPTION

HyperX HX432C16PB3K4/16 is a kit of four 512M x 64-bit (4GB) DDR4-3200 CL16 SDRAM (Synchronous DRAM) 1Rx8, memory module, based on eight 512M x 8-bit FBGA components per module. Each module kit supports Intel® Extreme Memory Profiles (Intel® XMP) 2.0. Total kit capacity is 16GB. Each module has been tested to run at DDR4-3200 at a low latency timing of 16-18-18 at 1.35V. The SPDs are programmed to JEDEC standard latency DDR4-2400 timing of 17-17-17 at 1.2V. Each 288-pin DIMM uses gold contact fingers. The JEDEC standard electrical and mechanical specifications are as follows:

FEATURES

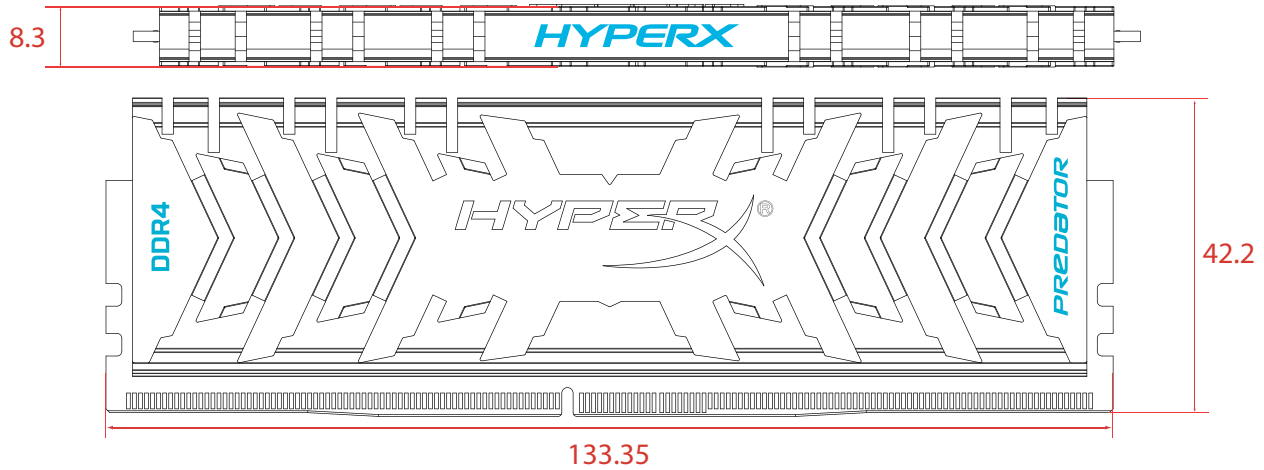
- Power Supply: VDD = 1.2V Typical
- VDDQ = 1.2V Typical
- VPP - 2.5V Typical
- VDDSPD = 2.25V to 3.6V
- On-Die termination (ODT)
- 16 internal banks; 4 groups of 4 banks each
- Bi-Directional Differential Data Strobe
- 8 bit pre-fetch
- Burst Length (BL) switch on-the-fly BL8 or BC4(Burst Chop)
- Height 1.661" (42.20mm)

XMP TIMING PARAMETERS

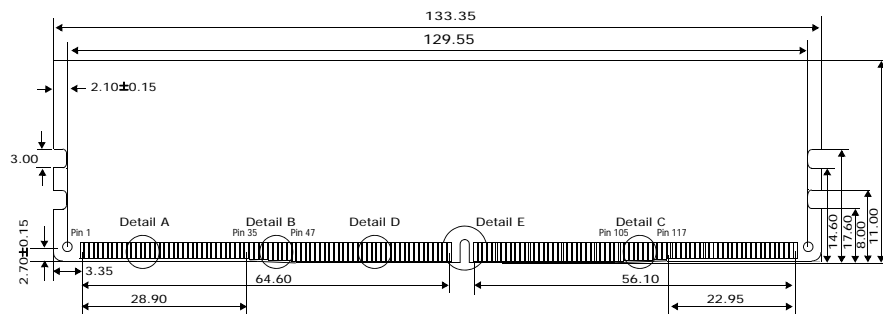
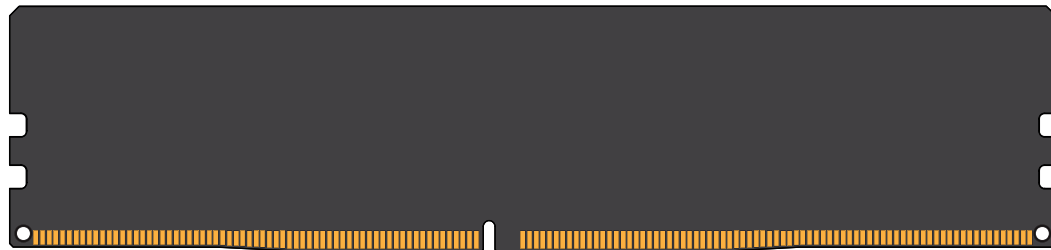
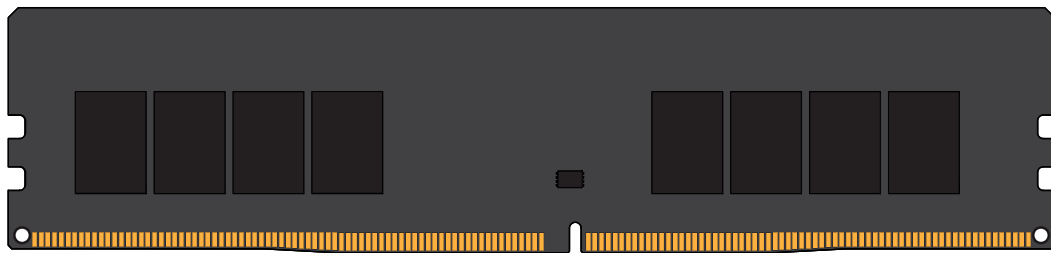
- JEDEC: DDR4-2400 CL17-17-17 @1.2V
- XMP Profile #1: DDR4-3200 CL16-18-18 @1.35V
- XMP Profile #2: DDR4-3000 CL15-17-17 @1.35V

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MODULE WITH HEAT SPREADER



MODULE DIMENSIONS



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All Kingston products are tested to meet our published specifications. Some motherboards or system configurations may not operate at the published HyperX memory speeds and timing settings. Kingston does not recommend that any user attempt to run their computers faster than the published speed. Overclocking or modifying your system timing may result in damage to computer components.